ESPECIFICACIONES TECNICAS



	1. Support for 7 th and 6 th generation Intel Core I7 processors/Intel Core I5 processors/Intel Core i3
CPU	processors/Intel Pentium processors/Intel Celeron processors in the LGA 1151 Package
	2. L3 cache varies with CPU
CHIPSET	1. Intel B250 Express Chipset
MEMORY	1. 4 x DRR4 DIMM sockets supporting up to 64 GB of system memory
	2. Dual channel memory architecture
	3. Support for DDR4 2400*/ 2133 MHz memory modules
	4. Support for ECC Un-Buffered DIMM 1Rx8/2Rx8memory modules (operate in non-ECC mode)
	5. Support for non-ECC Un-Buffered DIMM 1Rx8/2Rx8/1Rx16 memory modules
	6. Support for Extreme Memory Profile (XMP) memory modules
ONBOARD GRAPHICS	
AUDIO	
LAN	
EXPANSION SLOTS	
STORAGE INTERFACE	
USB	
INTERNAL I/O CONNECTORS	
BACK PANEL CONNECTORS	
I/O CONTROLLER	
H/W MONITORING	
BIOS	
UNIQUE FEATURES	
BUNDLED SOFTWARE	
OPERATING SYSTEM	
FORM FACTOR	